AB3505HB-QB3 ADDA 5VDC 35x35x5mm 0.11A Blower Fan Datasheet

Brand: ADDA

SKU: 753650651764

Category: Axial & Centrifugal Fans

Price: **$13.99**

E-mail: sales@equipspares.com

Web: https://www.equipspares.com

Product Page:
https://www.equipspares.com/product/ab3505hb-qb3-adda-5vdc-35x35x5mm-0-11a-blower-fan

Product Description

The ADDA AB3505HB-QB3 is a specialized DC Blower Fan engineered for ultra-compact thermal management applications requiring high static pressure in restricted spaces. Utilizing advanced DC brushless motor technology and a precision Ball Bearing architecture, this unit ensures consistent rotational stability and reduced frictional heat generation. The aerodynamic scroll housing is optimized to direct airflow efficiently, overcoming high thermal impedance in dense electronic assemblies. Its structural rigidity and slim profile make it an ideal solution for precision cooling tasks where reliability and spatial efficiency are paramount.

Model Number: AB3505HB-QB3
Brand: ADDA
Product Type: DC Blower Fan
Rated Voltage: 5VDC
Voltage Range: 4.5 - 5.5 VDC
Rated Current: 0.11 A
Power Consumption: 0.55 W
Rated Speed: 6500 RPM
Bearing Type: Ball Bearing
Max. Air Flow: 1.2 CFM (2.03 m^3/h / 0.03 m^3/min)
Max. Static Pressure: 5.8 mmH_2O (56.8 Pa / 0.23 inH_2O)

Dimensions: 35 x 35 x 5 mm
Weight: 8.5 g
Life Expectancy: 50,000 Hours at 40°C
Noise Level: 29.0 dB(A)
Termination: 3-Wire (Lead Wire)
Speed Control: Tachometer Output (FG Signal)
Housing Material: PBT Plastic (UL94V-0)
Impeller Material: PBT Plastic (UL94V-0)
Operating Temperature: -10°C to +70°C
Storage Temperature: -40°C to +70°C
Mounting Orientation: Any

The AB3505HB-QB3 is specifically designed for integration into ultra-portable electronics and projection equipment where vertical clearance is severely limited. Common deployment scenarios include cooling optical engines in portable USB projectors, thermal regulation in ultrabook laptops, and active cooling for compact embedded chipsets. The AB3505HB-QB3 provides the necessary static pressure to force air through dense heatsink fins found in these tightly packed enclosures, ensuring component longevity in mobile computing and multimedia devices.

Supplemental Images